

Product/process change notification

PCN N° 2022-098-A

Dear customer,

Please find attached our Infineon Technologies AG PCN:

Implementation of additional wafer production sites Infineon Technologies Dresden GmbH and Infineon Technologies Austria AG, Villach in 300 mm wafer size for IGBT4_1200V products in TO247 packages

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **2022-10-11**
- Infineon aligns with the widely recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.
We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.
For further details, please visit our website:
<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

Infineon Technologies AG
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Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider
Registered Office: Neubiberg
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► **Products affected**

Please refer to attached affected product list
1_cip22098_A

► **Detailed change information**

Subject Implementation of FE Dresden and Villach for the IGBT4_1200V Products in TO247 Packages.

Reason To free-up capacity in FE Kulim in 200 mm and to use the new available 300 mm corridor in Dresden and Villach

Description	<u>Old</u>	<u>New</u>
Wafer production and test site IGBT4_1200V	<ul style="list-style-type: none"> ■ Infineon Technologies (Kulim) Sdn. Bhd., Kulim 	<ul style="list-style-type: none"> ■ Infineon Technologies (Kulim) Sdn. Bhd., Kulim and Infineon Technologies Austria AG, Villach and Infineon Technologies Dresden GmbH
Wafer diameter	<ul style="list-style-type: none"> ■ 200 mm in Infineon Technologies (Kulim) Sdn. Bhd., Kulim 	<ul style="list-style-type: none"> ■ 200 mm in Infineon Technologies (Kulim) Sdn. Bhd., Kulim and 300 mm in Infineon Technologies Austria AG, Villach and 300 mm in Infineon Technologies Dresden GmbH

► **Product identification**

Internal traceability assured via lot code and development code.
External traceability assured via Product Bar Code Label / Lot Code

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▶ **Impact of change**

No Impact on parameters and reliability as proven via product qualification. Processes are optimized to meet identical product performance according to already applied Infineon specifications. Datasheet are available either on www.infineon.com or at your local sales office.

▶ **Attachments**

Please refer to attached affected product list
1_cip22098_A

▶ **Time schedule**

- | | |
|------------------------------|--|
| ■ Final qualification report | on request |
| ■ First samples available | on request |
| ■ Intended start of delivery | 2022-12-30 or earlier on specific customer request |

If you have any questions, please do not hesitate to contact your local sales office.

Sales name	SP number	OPN	Package
IGW15N120H3	SP000674430	IGW15N120H3FKSA1	PG-TO247-3
IGW25N120H3	SP000674424	IGW25N120H3FKSA1	PG-TO247-3
IGW40N120H3	SP000667510	IGW40N120H3FKSA1	PG-TO247-3
IKQ40N120CH3	SP001272706	IKQ40N120CH3XKSA1	PG-TO247-3
IKQ40N120CT2	SP001272732	IKQ40N120CT2XKSA1	PG-TO247-3
IKQ50N120CH3	SP001272708	IKQ50N120CH3XKSA1	PG-TO247-3
IKQ50N120CT2	SP001272736	IKQ50N120CT2XKSA1	PG-TO247-3
IKQ75N120CH3	SP001220142	IKQ75N120CH3XKSA1	PG-TO247-3
IKQ75N120CT2	SP001272740	IKQ75N120CT2XKSA1	PG-TO247-3
IKW15N120H3	SP000674422	IKW15N120H3FKSA1	PG-TO247-3
IKW15N120T2	SP000244961	IKW15N120T2FKSA1	PG-TO247-3
IKW25N120H3	SP000674418	IKW25N120H3FKSA1	PG-TO247-3
IKW25N120T2	SP000244960	IKW25N120T2FKSA1	PG-TO247-3
IKW40N120H3	SP000674416	IKW40N120H3FKSA1	PG-TO247-3
IKW40N120T2	SP000244962	IKW40N120T2FKSA1	PG-TO247-3
IKY40N120CH3	SP001465124	IKY40N120CH3XKSA1	PG-TO247-4
IKY50N120CH3	SP001465126	IKY50N120CH3XKSA1	PG-TO247-4
IKY75N120CH3	SP001465128	IKY75N120CH3XKSA1	PG-TO247-4

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Affected products sold to FUTURE ELECTRONICS INC. (4000624)

Sales name	SP number	OPN	Package	Customer part number
IKQ50N120CT2	SP001272736	IKQ50N120CT2XKSA1	PG-TO247-3	IKQ50N120CT2XKSA1
IKW25N120H3	SP000674418	IKW25N120H3FKSA1	PG-TO247-3	IKW25N120H3FKSA1
IKW25N120T2	SP000244960	IKW25N120T2FKSA1	PG-TO247-3	IKW25N120T2FKSA1
IKW40N120H3	SP000674416	IKW40N120H3FKSA1	PG-TO247-3	IKW40N120H3FKSA1
IKW40N120T2	SP000244962	IKW40N120T2FKSA1	PG-TO247-3	IKW40N120T2FKSA1